

AEC/APC Symposium Asia 2023 SPONSORSHIP

November 2, 2023, Tokyo, Japan

Hidetaka Nishimura
Chairman, AEC/APC Symposium Asia 2023 Executive Committee
Renesas Electronics Corporation

Hidenori Kakinuma
Chairman, AEC/APC Symposium Asia 2023 Program Committee
KIOXIA Corporation

It is our great pleasure to announce that The 9th annual AEC/APC Symposium Asia 2023 will be held on November 2, 2023 at National Center of Sciences Building (Gakujutsu Sogo Center), Tokyo which is sponsored by ISSM (International Symposium on Semiconductor Manufacturing).

The program is consist of keynote speech, tutorial speeches, oral speeches, poster presentations and supplier exhibition. This year, the symposium puts the subtitle” *Towards unraveling the complexity, share best practices in data science*”.

AEC/APC Symposium Asia continues to contribute to the growth of the semiconductor industry through its infrastructure for networking, discussion, and information sharing among the world's professionals. We would like you to cooperate with us by supporting the AEC/APC Symposium Asia 2023.

Please see the benefit of AEC/APC Symposium Asia 2023 sponsorship.

Conference Overview

Date: November 2, 2023
Location: National Center of Sciences Building (Gakujutsu Sogo Center)
2-1-2 Hitotsubashi Chiyoda-ku, Tokyo 101-0003, Japan
Tel: +81 3 4212-3900 Fax: +81 3 4212-3910
Sponsored by: International Symposium on Semiconductor Manufacturing (ISSM)
Supported by: Japan Electronics and Information Technology Industries Association
Semiconductor Equipment Association of Japan (SEAJ)
Semiconductor Equipment and Materials International (SEMI)
In conjunction with: Dry Process Symposium (DPS)

About AEC/APC Symposium

AEC/APC symposium calls its annual conference in North America, Europe, and Asia. The suppliers of the device, the equipment, the material, the software, the sensor, and the metrology shall meet, and discuss the more intelligent and the higher productive manufacturing system in the conferences. The conference is held in Taiwan and Japan every other year. AEC/APC is called the core of the scientific manufacturing technology. The technology has created the extensive progress of the productivity improvement and the yield improvement in the semiconductor manufacturing area. The technology discussed in the conferences has been applied and used in the process technology of LCD,PV and Battery.

In Japan, the 9th conference is called in this year. Since 2007, the conference has discussed the scientific manufacturing technology using the data which can monitor the manufacturing equipment and the process conditions.

The symposium is a very good chance among the technical authorities from Japan and from out of Japan to share their knowledge and technologies in AEC/APC area. The symposium can also be a very good chance for the professionals of the process control industry such as semiconductor to meet and discuss.

Today, this area already forms the core part of the manufacturing engineering technology.

The role of this symposium is very important, since people can share the information and the directions of the process control improvement, the equipment productivity improvement, and the material source reduction for the future.

Organization

Japan Executive Committee

Chair	Hidetaka Nishimura	Renesas Electronics Corporation
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Japan Program Committee

Chair	Hidenori Kakinuma	Kioxia Corporation
Vice-Chair	Sumika Arima	University of Tsukuba
Members	Takashi Kurosawa	Azbil Corporation
	Masahiko Senzaki	Azbil Corporation
	Akira Kagoshima	Hitachi High-Tech Corporation
	Osamu Ohishi	IBM Japan Digital Services Company
	Koh Horimoto	IBM Japan Digital Services Company
	Hirofumi Tsuchiyama	INFICON Co.,Ltd
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	Toshiya Hirai	KOKUSAI ELECTRIC CORPORATION
	Kenji Miyake	Office Miyake
	Tsuyoshi Miyatake	Renesas Electronics Corporation
	Shunichi Shibuki	Sony Semiconductor Manufacturing Corporation
	Koichi Sakamoto	Tokyo Electron Ltd.
	Hisato Tanaka	Tokyo Electron Ltd.
	Kazutaka Nagashima	Toshiba Electronic Devices & Storage Corporation
Tomoya Tanaka	Tower Partners Semiconductor Co., Ltd.	
Takahiro Tsuchiya	United Semiconductor Japan Co., Ltd.	

AEC/APC Symposium Asia Advisor

Advisor	Koji Maekawa	Addison Clear Wave Coatings Inc.
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AEC/APC Symposium Asia 2023 Sponsorship

Application Form

<https://www.semiconportal.com/r/69/registration.php>

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Sponsorship Fee	¥800,000	¥500,000	¥300,000	¥80,000
AEC/APC Symposium Asia Invitation (Free)				
Free ticket(s) for AEC/APC Symposium Asia (Tutorial session excluded)	12	7	4	1
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Company logo placed on homepage	Yes	Yes	Yes	Yes
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Link to company homepage	Yes	Yes	Yes	Yes
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Recognition of sponsorship in meeting materials along with company logo and link to corporate website (User would need to have Internet access when viewing the proceedings)	Upper	Middle	Lower	Lower
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List				
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AEC/APC Symposium Asia 2023 Exhibition

Exhibition (with Sponsorship)	¥100,000
Exhibition Only	¥120,000

Contact:

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C/O Semiconductor Portal, Inc.

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